

SOT961-1

plastic very thin fine-pitch ball grid array package; 352 balls;
top 128 lands; stackable; body 12 x 12 x 0.65 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA352S
Package type industry code	VFBGA352S
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	S (stackable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-8-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.8	-	12	12.2	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	[tbd]	-	1	1	mm
A ₂	package height	0.58	-	0.65	0.72	mm
n ₂	actual quantity of termination	-	-	352	-	



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2. Package outline

VFBGA352S: plastic very thin fine-pitch ball grid array package; 352 balls; top 128 lands; stackable; body 12 x 12 x 0.65 mm

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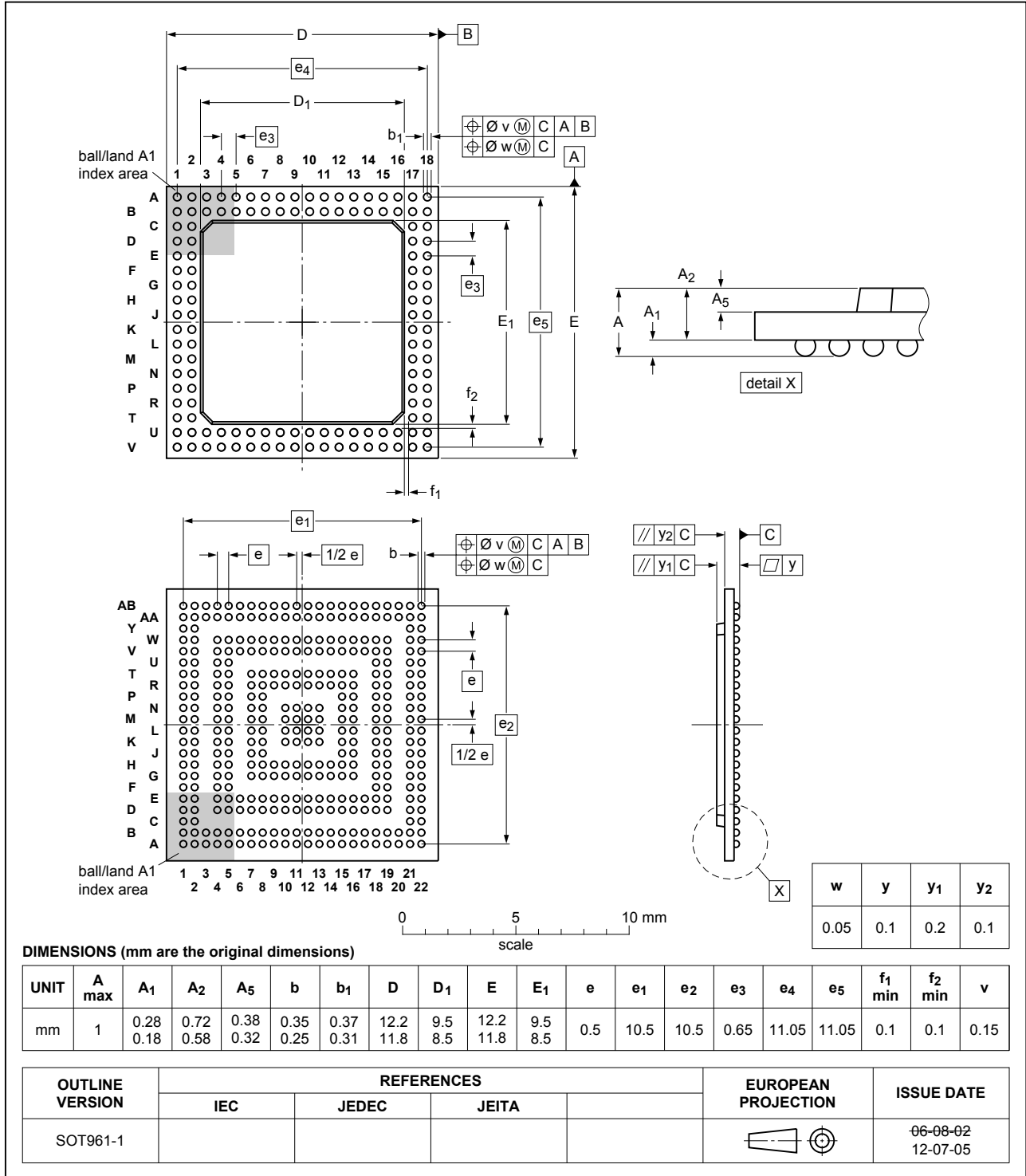


Fig. 1. Package outline VFBGA352S (SOT961-1)

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3. Legal information

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